WEIDACHENG INDUSYRY CO.,LTD

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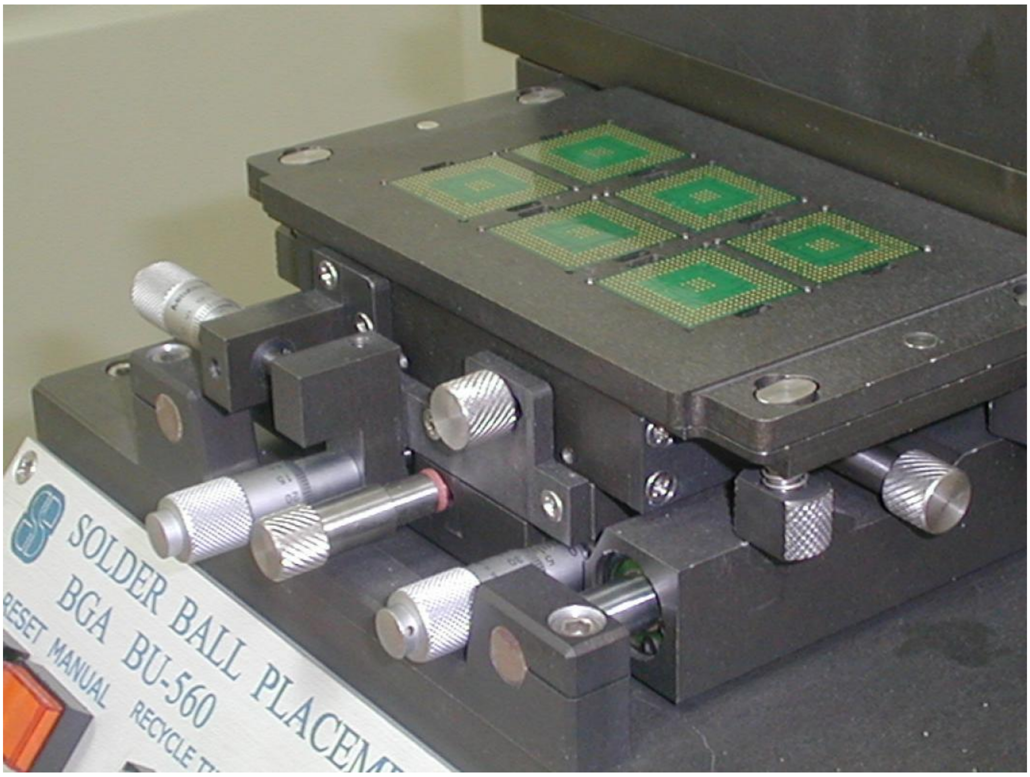
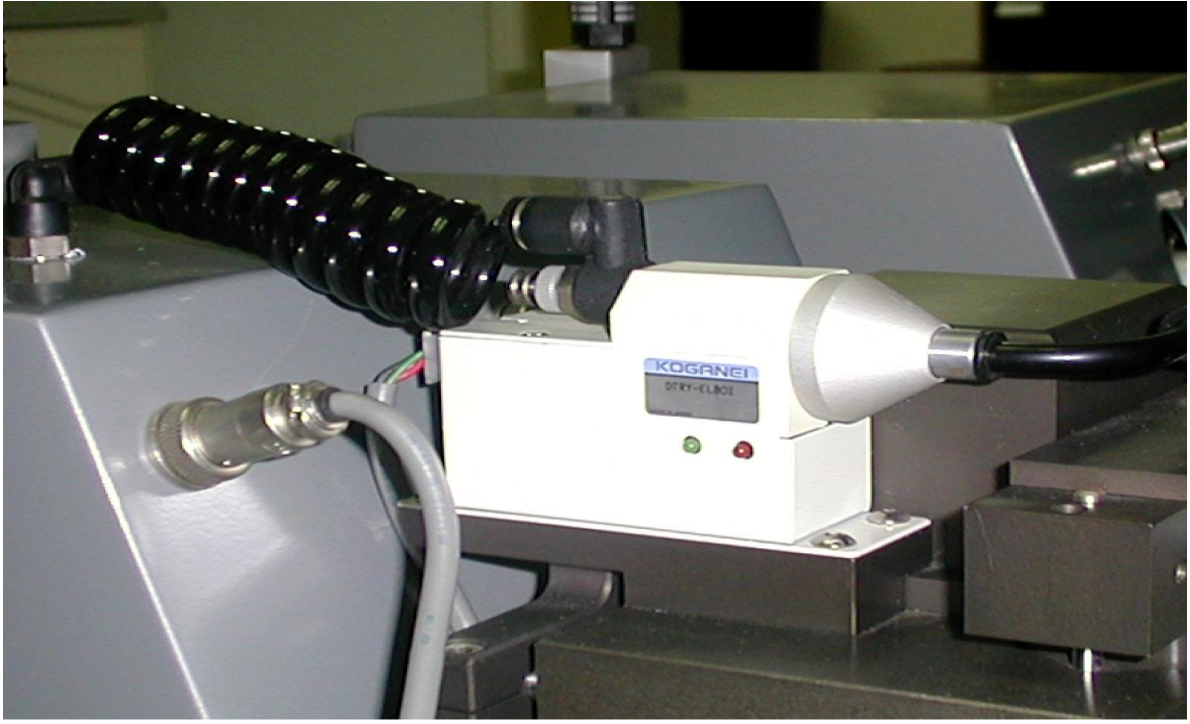
SOLDERING PLACEMENT' SYSTEM BU-560

Ball placement capability:Φ 0.35 ~**Φ** 0.76 Ball placement range:L-65mm.W-80mm

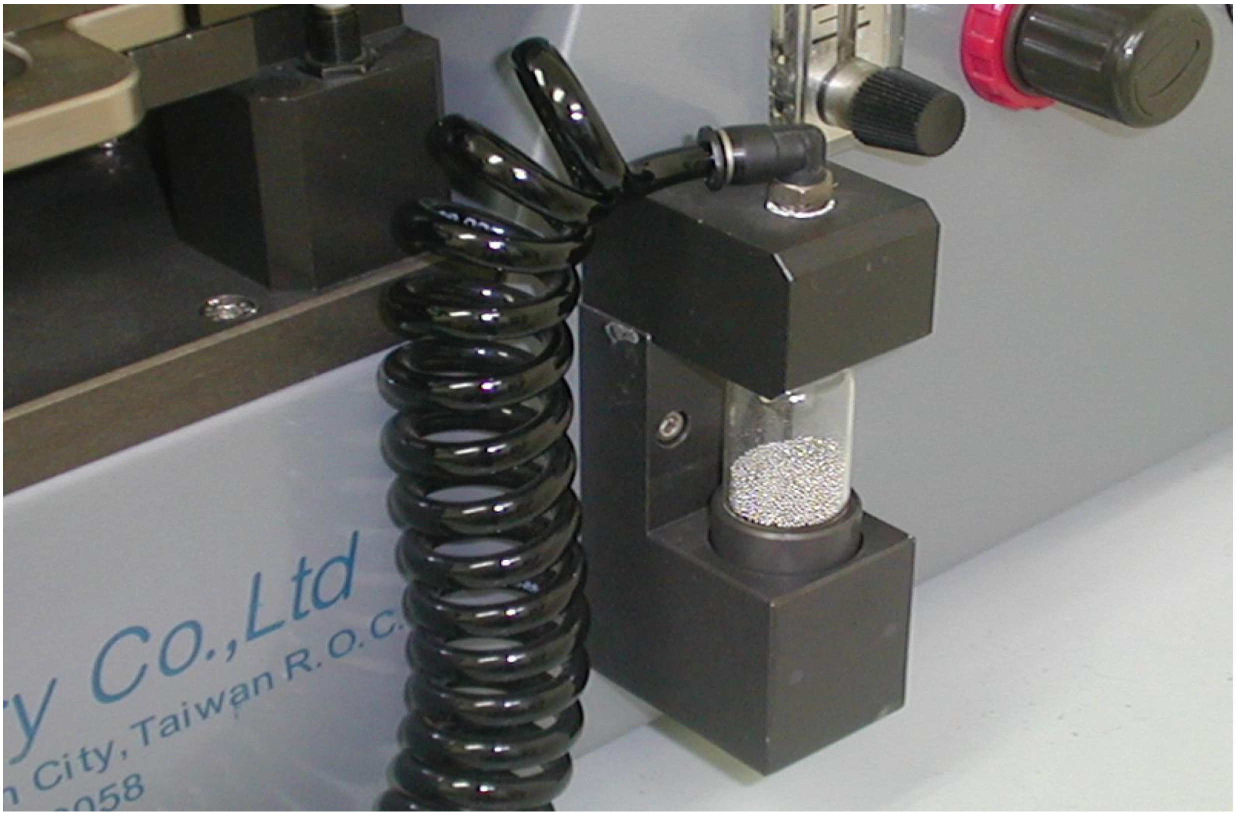
X-Y-θ Theta positioning slider with micrometers adjustment & BGA fixtures.



Ionic electrostatic remover(eliminate electrical charge on solder balls)

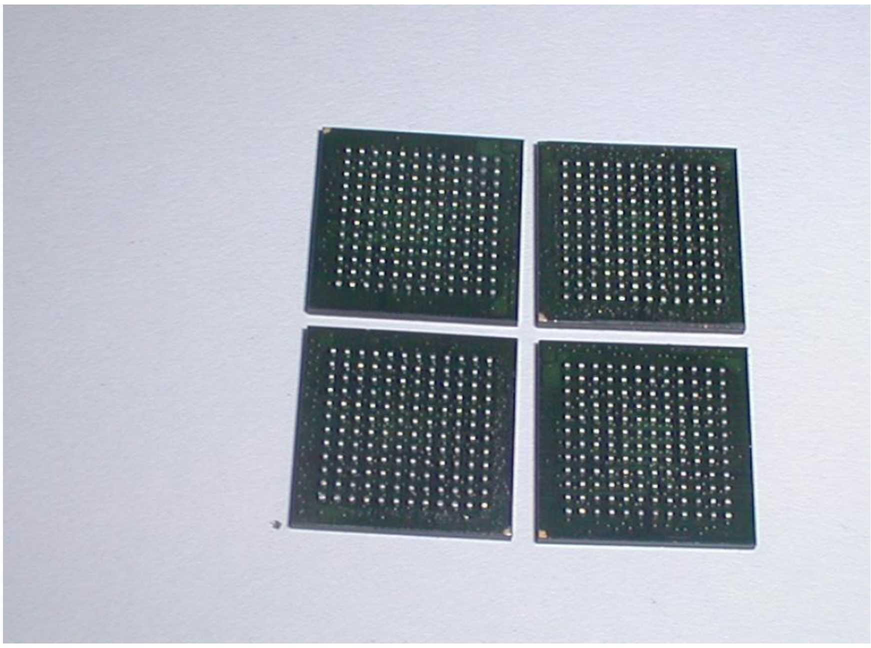


Solder ball collecting bottle base. (Ball cleaning device)



Drawable solder ball mask cassette base.

All kinds of solder ball placement tooling for BGA IC.



BGA rework equipment -- Solder ball placement system BU-560

(1) ■ Outside dimension: 75cm(L), 25cm(W), 26cm(H).

(2) ■ Weight: 32 kg.

(3) ■ Working voltage: 110/220V;50/60Hz

(4) ■ Working air pressure: 6 kg/cm^2.

(5) ■ Solder ball specification: According to the solder ball spec being used by different kinds of BGA package.

(6) ■ BGA IC holder: It is available for changing-over different types of BGA IC holders according to different size or spec of BGA package.

(7) ■ Solder ball screening fixture: It is available for changing-over different ball screening fixtures according to different size or spec of solder ball.

(8) ■ Solder ball placing speed: The speed for placing solder balls onto BGA pads can be adjusted and fine-tuning controlled.

(9) ■ Ball-placing yield rate: 98%.

(10) ■ Ball-placing accuracy: 0.03mm.

(11) ■ BGA IC holder unloading speed: Unloading speed 30~300 mm/s.

(12) ■ Automatic ball-placing operation cycle time : 22 seconds.

BGA regeneration!

~ Place solder balls on BGA to regenerate a whole new one with the lowest cost. ~

The solder ball placement system places new solder balls again onto ball removed BGA-IC for new reflowing rework. This equipment provides a technology promotion for traditional BGA operation in SMT industry. It is a very useful tool for BGA production.

[There are patents approved by lots of countries for this equipment. All rights are reserved]